

Title (en)
ELECTRODEPOSITION OF ALUMINUM AND REFRACTORY METALS FROM NON-AROMATIC ORGANIC SOLVENTS

Title (de)
ELEKTROPLATTIERUNG VON ALUMINIUM UND REFRAKTÄRMETALLEN AUS EINER NICHTAROMATISCHEN ORGANISCHEN LÖSUNG

Title (fr)
ELECTRODEPOSITION D'ALUMINIUM ET METAUX REFRACTAIRES ELABORES A PARTIR DE SOLVANTS ORGANIQUES NON AROMATIQUES

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Application
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Priority

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- US 45163103 P 20030305
- US 79183504 A 20040304

Abstract (en)
[origin: US2004173468A1] An electroplating solution includes a non-aqueous non-aromatic organic solvent and a mixture including soluble metallic salts and organic additives dissolved in the non-aqueous non-aromatic organic solvent. Electrodeposition of a metal from the electroplating solution includes preparing an electroplating solution and electrodepositing the metal from the electroplating solution onto a conductive substrate under a cathodic current. An electroplating system has a plating chamber containing an electroplating solution, an entry point to the electroplating system, and a transporting system to convey a part to be electroplated from the entry point to the plating chamber. The electroplating solution includes a non-aqueous non-aromatic organic solvent and a mixture including soluble metallic salts and organic additives, the mixture dissolved in the non-aqueous non-aromatic organic solvent.

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